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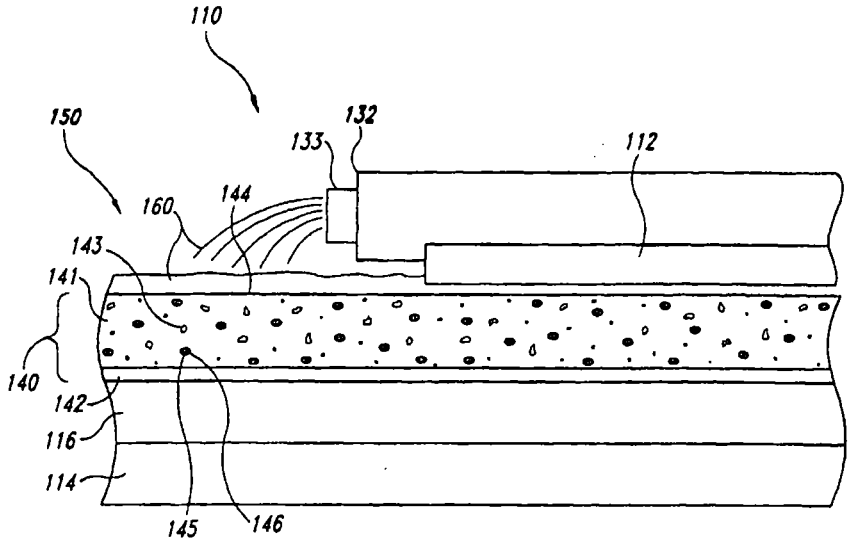
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(54) Title: METHOD AND APPARATUS FOR CONTROLLING CHEMICAL INTERACTIONS DURING PLANARIZATION OF MICROELECTRONIC SUBSTRATES



(57) Abstract: A method and apparatus for planarizing a microelectronic substrate. In one embodiment, the microelectronic substrate is engaged with a planarizing medium that includes a planarizing pad and a planarizing liquid, at least one of which includes a chemical agent that removes a corrosion-inhibiting agent from discrete elements (such as abrasive particles) of the planarizing medium and/or impedes the corrosion-inhibiting agent from coupling to the discrete elements. The chemical agent can act directly on the corrosion-inhibiting agent or can first react with a constituent of the planarizing liquid to form an altered chemical agent, which then interacts with the corrosion-inhibiting agent. Alternatively, the altered chemical agent can control other aspects of the manner by which material is removed from the microelectronic substrate, for example, the material removal rate.

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